



SOT1571-5

plastic, thermal enhanced low profile quad flat package; 48 leads; body 7 x 7 x 1.5 mm

14 July 2016

Package information

1. Package summary

Dimensions (mm)	7 x 7 x 1.5
Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package outline version code	SOT1571-5
Manufacturer package code	SOT1571
Package type industry code	HLQFP
Package outline version description	plastic, thermal enhanced low profile quad flat package; 48 leads; body 7 x 7 x 1.5 mm
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P
Mounting method type	S (surface mount)
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	14-7-2016
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	1.35	-	1.4	1.45	mm
A	seated height	1.4	-	1.5	1.6	mm
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
e	nominal pitch	-	-	0.5	-	mm



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2. Package outline

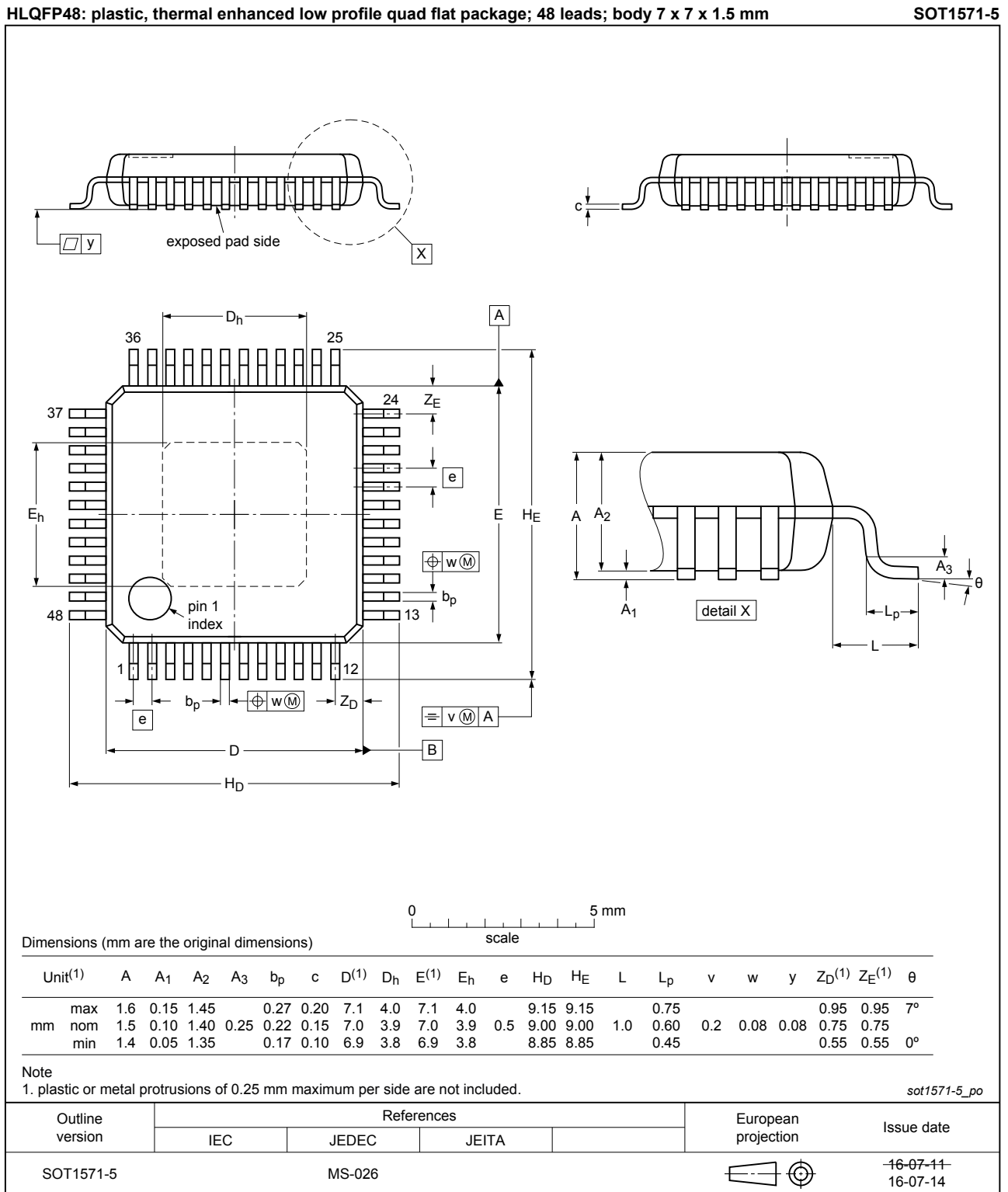


Fig. 1. Package outline HLQFP (SOT1571-5)

3. Legal information

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